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(54) PLATING JIG

insulating plate 4,

(57) Abstract:

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PROBLEM TO BE SOLVED: To improve uniformity of the thickness of a thin film to be formed by electroplating by stopping the supply of current to an wafer by means of a contact and uniformly supplying the current from the entire circumference of the wafer in connection with a plating jig which forms the uniform thin film by the electroplating and enables the wafer to be attachable and detachable.

SOLUTION: The plating jig is constituted of a principal electrode plate 3 which comes in contact with the entire surface of the outer circumference of the wafer 1, a contractable insulating plate 4 which allows this principal electrode plate 3 to uniformly contact with the entire surface of the outer circumference of the wafer 1, an auxiliary electrode plate 5 which is provided on this insulating plate 4 and forms an auxiliary current distribution for forming the uniformly thick thin film on the wafer 1, and a wafer-pressing plate 7 which is brought into contact with the entire periphery of the outer circumference by exerting a force in the compressive direction between the wafer 1 and the

